

P-Channel Enhancement Mode Field Effect Transistor

NDS0610

General Description

This P-Channel Enhancement Mode Field Effect Transistors are Produced using onsemi's proprietary, high cell density, DMOS technology. This very high density process has been designed to minimize on-state resistance, provide rugged and reliable performance and fast switching. They can be used, with a minimum of effort, in most applications requiring up to 120 mA DC and can deliver current up to 1 A.

This product is particularly suited to low voltage applications requiring a low current high side switch.

Features

- -0.12 A, -60 V
 - ◆ $R_{DS(on)} = 10 \Omega @ V_{GS} = -10 V$
 - ◆ $R_{DS(on)} = 20 \Omega @ V_{GS} = -4.5 V$
- Voltage Controlled P-Channel Small Signal Switch
- High Density Cell design for Low $R_{DS(on)}$
- High Saturation Current

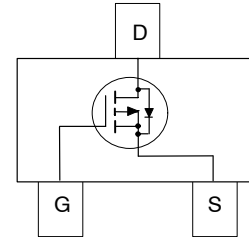
ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Value	Unit
V_{DSS}	Drain to Source Voltage	-60	V
V_{GSS}	Gate to Source Voltage	± 20	V
I_D	Drain Current - Continuous (Note 1) - Pulsed	-0.12 -1	A
P_D	Maximum Power Dissipation (Note 1)	0.36	W
	Derate Above 25°C	2.9	
T_J, T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C
T_L	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300	°C

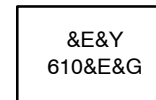
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



SOT-23
CASE 318-08



MARKING DIAGRAM



&E = Space on marking
&Y = Year Code
610 = Device marking
&E = Space on marking
&G = Weekly Date Code

ORDERING INFORMATION

Device	Package	Shipping†
NDS0610	SOT-23 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

NDS0610

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	350	°C/W

ELECTRICAL CHARACTERISTICS $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -10\ \mu\text{A}$	-60	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -10\ \mu\text{A}$, Referenced to 25°C	-	-53	-	mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -48\text{ V}, V_{GS} = 0\text{ V}$	-	-	-1	μA
		$V_{DS} = -48\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$	-	-	-200	μA
I_{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	± 10	nA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -1\text{ mA}$	-1	-1.7	-3.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -1\text{ mA}$, Referenced to 25°C	-	-3	-	mV/°C
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -0.5\text{ A}$ $V_{GS} = -4.5\text{ V}, I_D = -0.25\text{ A}$ $V_{GS} = -10\text{ V}, I_D = -0.5\text{ A}, T_J = 125^\circ\text{C}$	-	1.0 1.3 1.7	10 20 16	Ω
$I_{D(on)}$	On-State Drain Current	$V_{GS} = -10\text{ V}, V_{DS} = -10\text{ V}$	-0.6	-	-	A
g_{FS}	Forward Transconductance	$V_{DS} = -10\text{ V}, I_D = -0.1\text{ A}$	70	430	-	mS

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -25\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	-	79	-	pF
C_{oss}	Output Capacitance		-	10	-	pF
C_{rss}	Reverse Transfer Capacitance		-	4	-	pF
R_G	Gate Resistance	$V_{DS} = -15\text{ mV}, f = 1.0\text{ MHz}$	-	10	-	Ω

Switching Characteristics (Note 2)

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -25\text{ V}, I_D = -0.12\text{ A},$ $V_{GS} = -10\text{ V}, R_{GEN} = 6\ \Omega$	-	2.5	5	ns
t_r	Turn-On Rise Time		-	6.3	12.6	ns
$t_{d(off)}$	Turn-Off Delay Time		-	10	15	ns
t_f	Turn-Off Fall Time		-	7.5	15	ns
Q_g	Total Gate Change	$V_{DS} = -48\text{ V}, I_D = -0.5\text{ A},$ $V_{GS} = -10\text{ V}$	-	1.8	2.5	nC
Q_{gs}	Gate-Source Change		-	0.3	-	nC
Q_{gd}	Gate-Drain Change		-	0.4	-	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	-	-	-0.24	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -0.24\text{ A}$ (Note 2)	-	-0.8	-1.5	V
t_{rr}	Diode Reverse Recovery Time	$I_F = -0.5\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$ (Note 2)	-	17	-	ns
Q_{rr}	Diode Reverse Recovery Charge		-	15	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

- $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) $350\ \text{°C/W}$ when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

- Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2.0\%$

TYPICAL CHARACTERISTICS

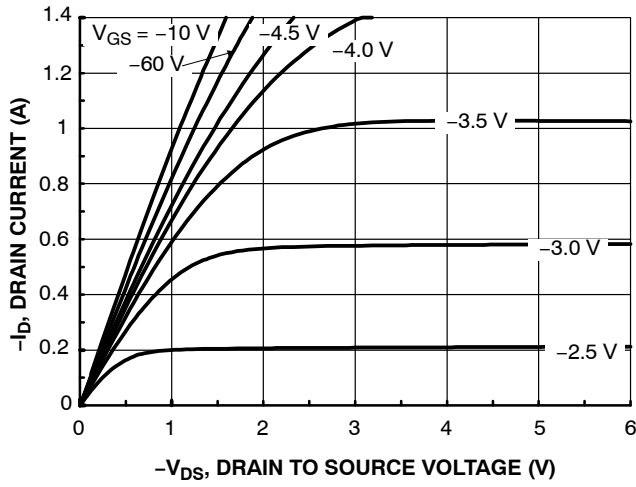


Figure 1. On-Region Characteristics

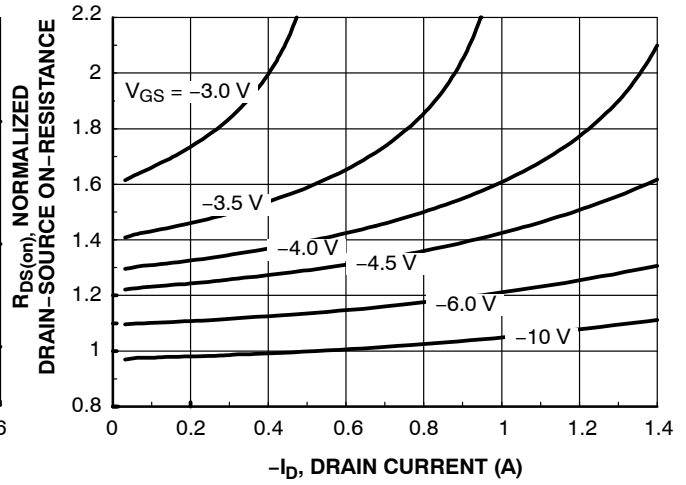


Figure 2. On-Resistance Variation With Drain Current and Gate Voltage

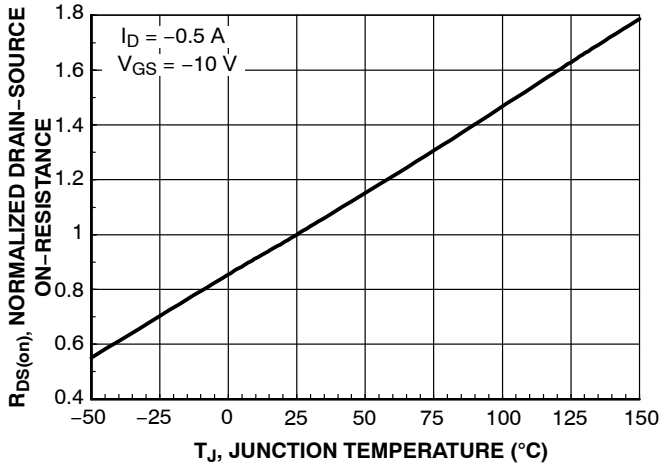


Figure 3. On-Resistance Variation with Temperature

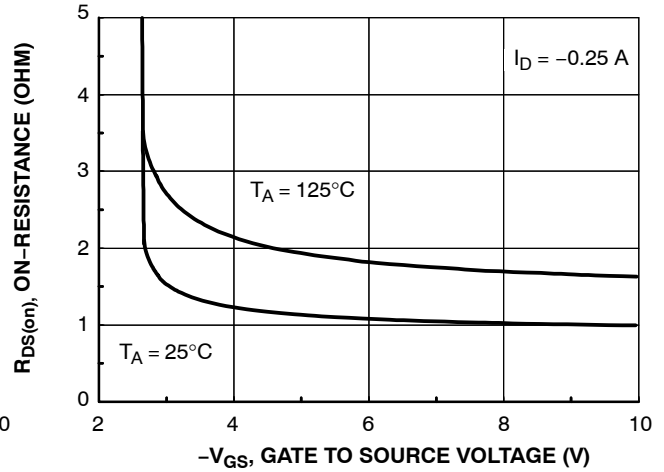


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

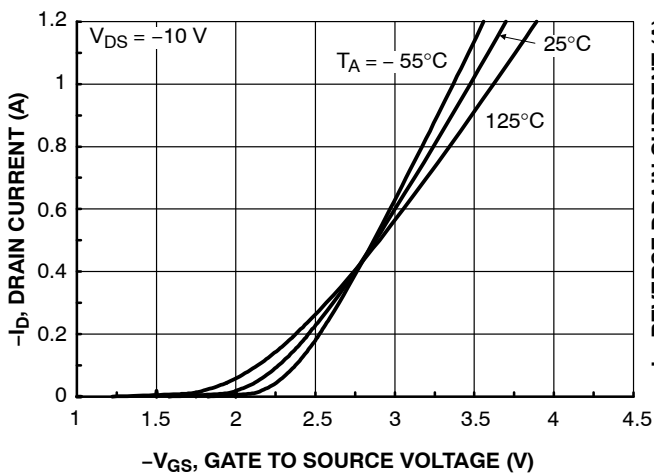


Figure 5. Transfer Characteristics

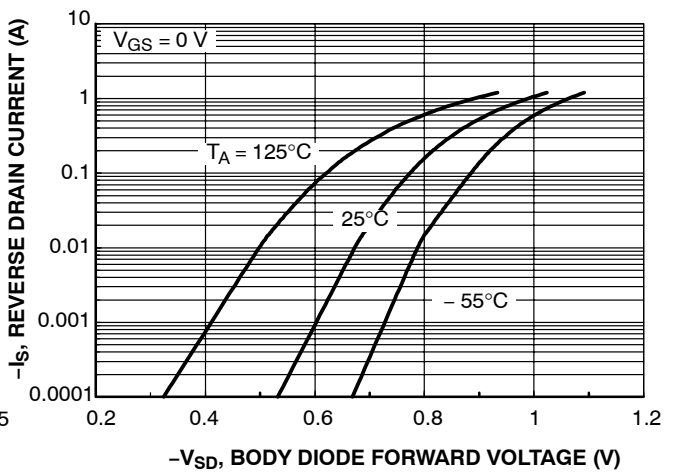


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

TYPICAL CHARACTERISTICS (CONTINUED)

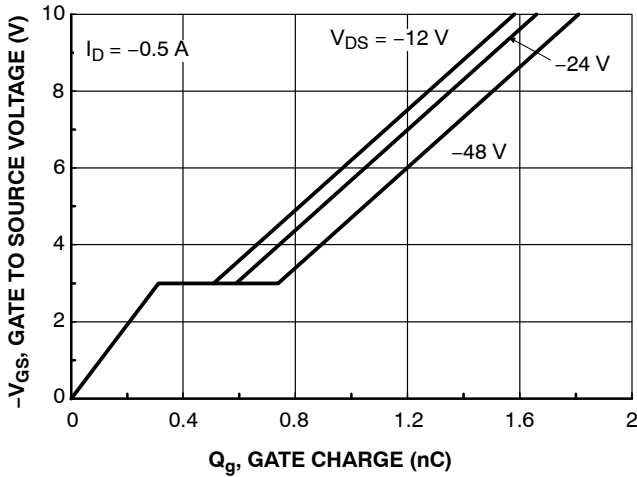


Figure 7. Gate Charge Characteristics

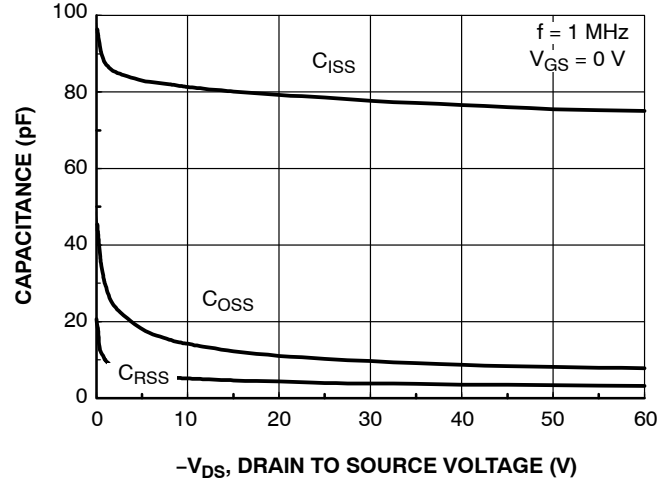


Figure 8. Capacitance Characteristics

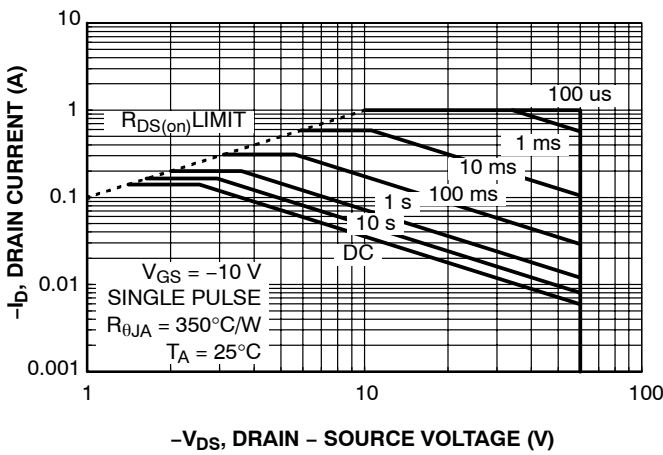


Figure 9. Maximum Safe Operating Area

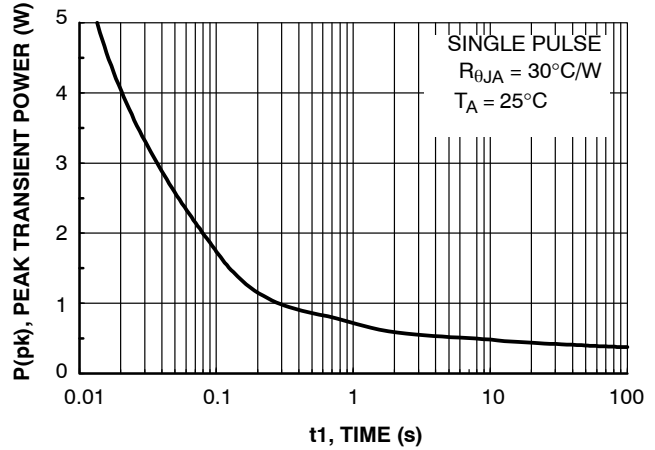


Figure 10. Single Pulse Maximum Power Dissipation

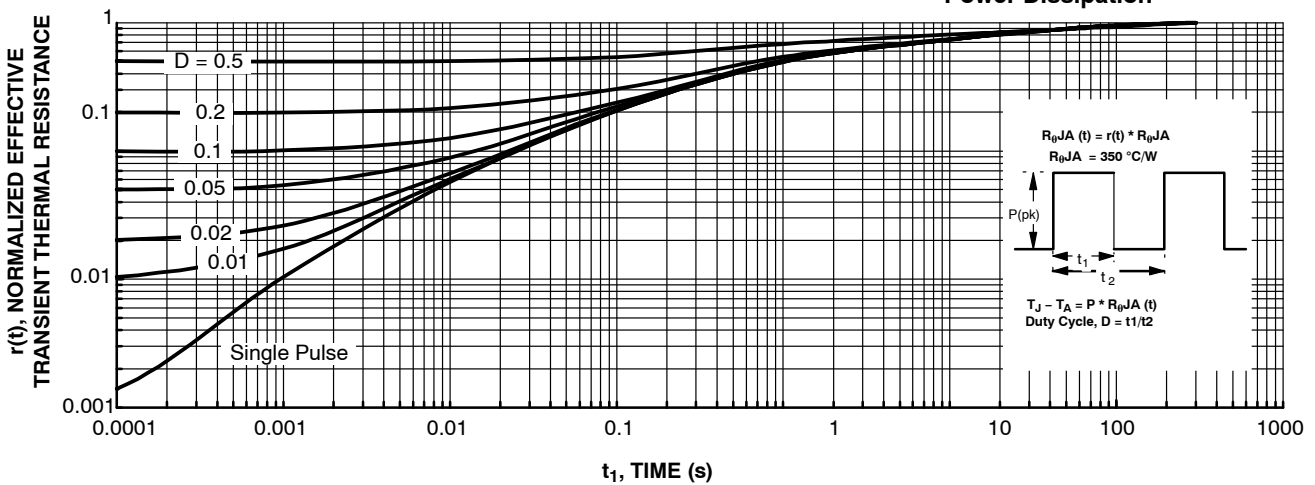
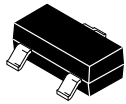


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1a. Transient thermal response will change depending on the circuit board design.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

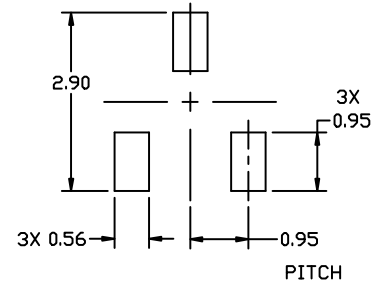
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H _E	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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**MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS**



**SOT-23 (TO-236)
CASE 318
ISSUE AT**

DATE 01 MAR 2023

- | | | | | | |
|---|---|---|---|---|---|
| STYLE 1 THRU 5:
CANCELLED | STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR | STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR | STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE | | |
| STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE | STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE | STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE | STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE | STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE | STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE |
| STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE | STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE | STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE | STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE | STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE-ANODE | STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE |
| STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN | STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT | STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE | STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE | STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE | STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION |
| STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE | STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE | | | | |

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